Unit: mm

TOSHIBA Schottky Barrier Diode

CRS05

- Secondary Rectification in Switching Regulators
- Reverse-Current Protection in Mobile Devices

• Repetitive peak reverse voltage $: V_{RRM} = 30 \text{ V}$ • Average forward current $: I_F (AV) = 1.0 \text{ A}$

• Peak forward voltage $\begin{array}{ll} : V_{FM} = 0.45 \ V \ (max) \ @I_{FM} = 1.0 \ A \\ \\ \bullet & \text{Repetitive peak reverse current} \end{array} \\ : I_{RRM} = 5 \ \mu A \ (max) \ @V_{RRM} = 5 \ V \\ \end{array}$

 The use of small, thin surface-mount package is optimum way for high-density mounting

for high-density mounting. Nickname: $S\text{-}FLAT^{TM}$

Absolute Maximum Ratings (Ta = 25°C)

| Characteristics | Symbol | Rating | Unit | |
|---|------------------|---------------------|------|--|
| Repetitive peak reverse voltage | V _{RRM} | V _{RRM} 30 | | |
| Average forward current | le.m.o | 1.0 (Note 1) | Α | |
| Average lorward current | lF(AV) | 1.0 (Note 2) | ^ | |
| Non-repetitive peak forward surge current | I _{FSM} | 20 (50 Hz) | Α | |
| Junction temperature | Tj | −40 to 150 | °C | |
| Storage temperature | T _{stg} | −40 to 150 | °C | |

Note 1: Ta = 102°C Device mounted on a ceramic board

board size : $50 \text{ mm} \times 50 \text{ mm}$ Soldering land size : $2 \text{ mm} \times 2 \text{ mm}$ board thickness : 0.64 mm

Rectangular waveform $\,:\, \alpha$ = 180°, V_R = 15 V

Note 2: Ta = 54.7°C Device mounted on a glass-epoxy board

 $\begin{array}{lll} \text{board size} & : 50 \text{ mm} \times 50 \text{ mm} \\ \text{Soldering land size} & : 6 \text{ mm} \times 6 \text{ mm} \\ \text{board thickness} & : 1.6 \text{ mm} \end{array}$

Rectangular waveform : $\alpha = 180^{\circ}$, VR = 15 V

JEDEC —

JEITA —

TOSHIBA 3-2A1S

Weight: 0.013 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

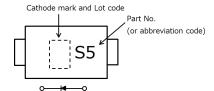
Electrical Characteristics (Ta = 25°C)

| Characteristics | Symbol | Test Condition | Min | Тур. | Max | Unit | |
|--|-----------------------|---|-----|------|------|------|--|
| | V _{FM (1)} | I _{FM} = 0.1 A (pulse test) | _ | 0.33 | _ | | |
| Peak forward voltage | VFM (2) | IFM = 0.7 A (pulse test) | _ | 0.40 | _ | ٧ | |
| | VFM (3) | I _{FM} = 1.0 A (pulse test) | _ | 0.42 | 0.45 | | |
| Repetitive peak reverse current | I _{RRM (1)} | V _{RRM} = 5 V (pulse test) | _ | 2.0 | 5.0 | | |
| | IRRM (2) | V _{RRM} = 30 V (pulse test) | _ | 20 | 200 | μΑ | |
| Junction capacitance | Cj | V _R = 10 V, f = 1.0 MHz | _ | 60 | _ | pF | |
| Thermal resistance (junction to ambient) | D | Device mounted on a ceramic board board size 50 mm × 50 mm soldering land size 2 mm × 2 mm board thickness 0.64 mm | _ | _ | 70 | °C/W | |
| | R _{th (j-a)} | Device mounted on a glass-epoxy board board size 50 mm × 50 mm soldering land size 6 mm × 6 mm board thickness 1.6 mm | _ | _ | 140 | C/VV | |

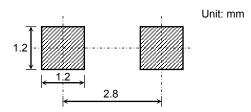
Start of commercial production 2000-07

Marking

| Abbreviation Code | Part No. | | |
|-------------------|----------|--|--|
| S5 | CRS05 | | |



Land pattern dimensions for reference only



Usage Considerations

Schottky barrier diodes have reverse current characteristics compared to other diodes.
 There is a possibility SBD may cause thermal runaway when it is used under high temperature or high voltage.
 Please take forward and reverse loss into consideration during design.

2) The absolute maximum ratings are rated values that must not be exceeded for a moment to have you use an element safely. Please refer to each following absolute maximum ratings on the occasion of use and design.

VRRM: VRRM has a temperature coefficient of 0.1 %/°C.

Please take this coefficient into account when designing a circuit board that will be operated in a low-temperature environment.

IF(AV): We recommend that the current be in less than 80 % of rating and the junction temperature (T_j)

be in less than 80 % of absolute maximum rating under the worst condition.

This rating is based on the premise that the device is radiating heat enough.

Therefore, when enough heat radiation is not expected, please consider the margin to the permission curve of $T_{a(max)}$ - $I_{F(AV)}$ for using the device.

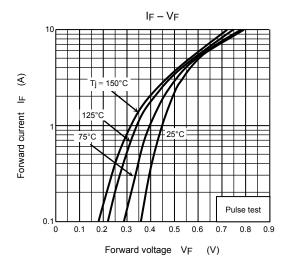
IFSM: This rating specifies a non-repetitive limit value.

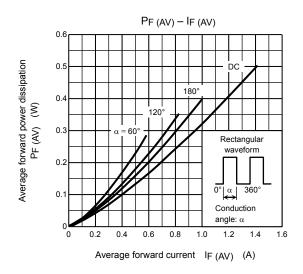
This only applies to an abnormal operation, which seldom occurs during the lifespan of a device.

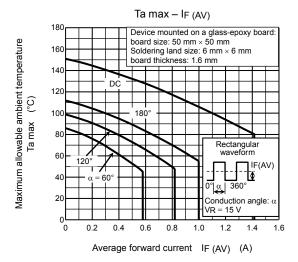
T_i: Derate device parameters in proportion to this rating in order to ensure high reliability.

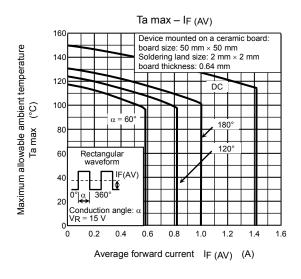
We recommend that the junction temperature (Ti) of a device be kept below 80 %.

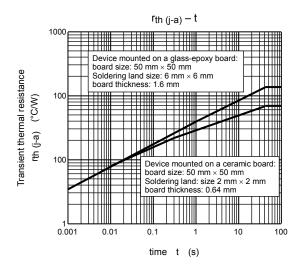
- 3) Thermal resistance (junction-to-ambient) varies with the mounting conditions of the device on the circuit board. An appropriate thermal resistance value that should be used, must be considering the circuit board design and soldering land size.
- 4) For other design considerations, see the Toshiba website.

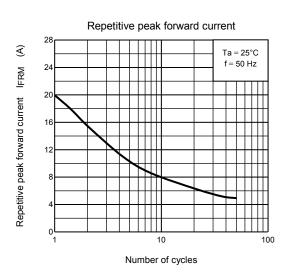




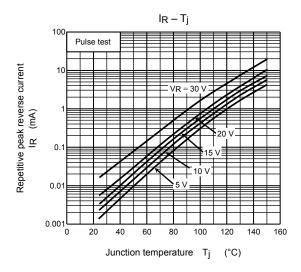


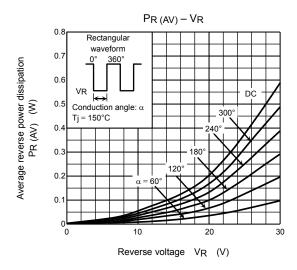


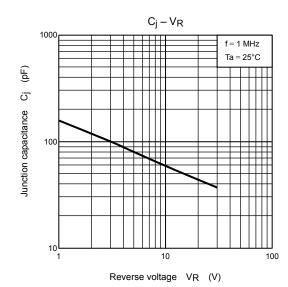




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